



QNHCHIP

QNM30ND20AJ

# Product Specification

**QNM30ND20AJ**

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30V Dual N-Channel MOSFET



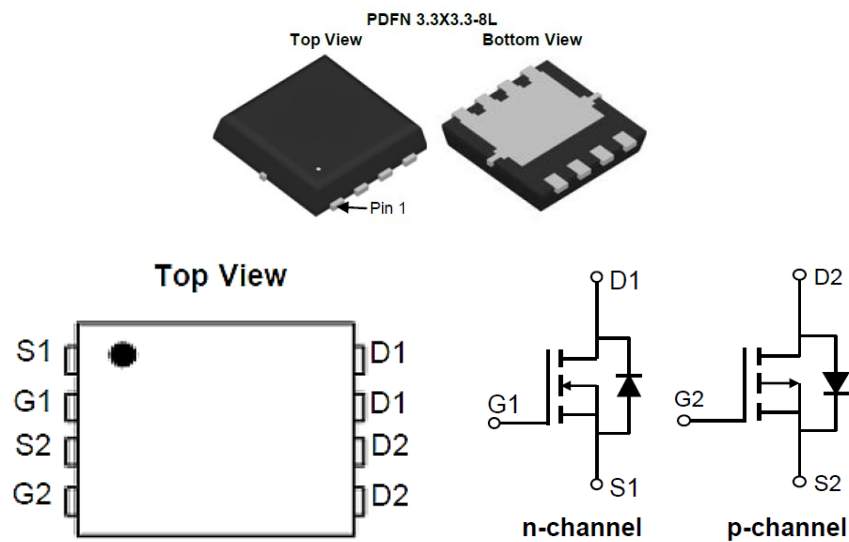
## FEATURES

- 30V, 22A  
 $R_{DS(ON)}$  Typ= 10.4m $\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)}$  Typ= 15.8m $\Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge

## Applications

- Load Switch
- PWM Application
- Power Management

## Pin Description



NO.	Symbol	Description
1	S1	SOURCE
2	G1	GATE
3	S2	SOURCE
4	G2	GATE
5	D1	DRAIN
6	D1	DRAIN
7	D2	DRAIN
8	D2	DRAIN



## Absolute Maximum Ratings

(@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{DS}$	Drain-to-Source Voltage		30	V
$V_{GS}$	Gate-to-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	22	A
		$T_C = 100^\circ\text{C}$	14	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>		88	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>		30	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	34	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>		59	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.7	
$T_J, T_{STG}$	Junction & Storage Temperature Range		-55 to 150	$^\circ\text{C}$



## Electrical Characteristics

(T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA V <sub>GS</sub> = 0V	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.6	2.2	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(4)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A	-	10.4	13.5	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	15.8	22.6	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	-	829	-	pF
C <sub>oss</sub>	Output Capacitance		-	96	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	77	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DD</sub> = 15V, I <sub>D</sub> = 20A	-	20	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	4	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	5	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 15V I <sub>D</sub> = 20A, R <sub>GEN</sub> = 3Ω	-	6	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	19	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	22	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	5	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	22	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	88	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 22A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> = 20A, di/dt = 100A/μs	-	8	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	2	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E<sub>AS</sub> condition: Starting T<sub>J</sub> = 25°C, V<sub>DD</sub> = 15V, V<sub>G</sub> = 10V, R<sub>G</sub> = 25ohm, L = 0.5mH, I<sub>AS</sub> = 11A
3. R<sub>θJA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB
4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 0.5%.



## Typical Performance Characteristics

Figure 1: Output Characteristics

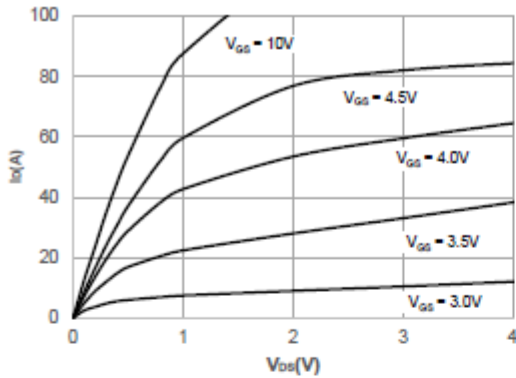


Figure 2: Typical Transfer Characteristics

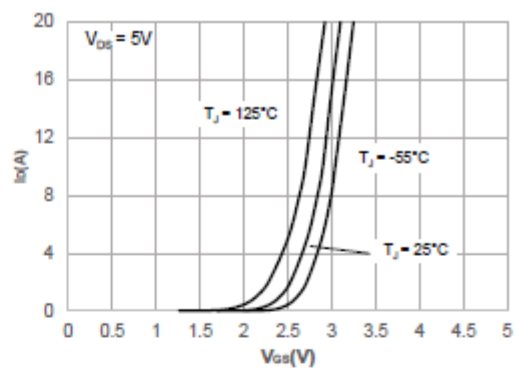


Figure 3: On-resistance vs. Drain Current

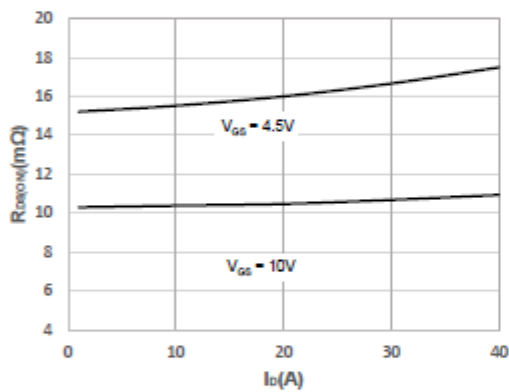


Figure 4: Body Diode Characteristics

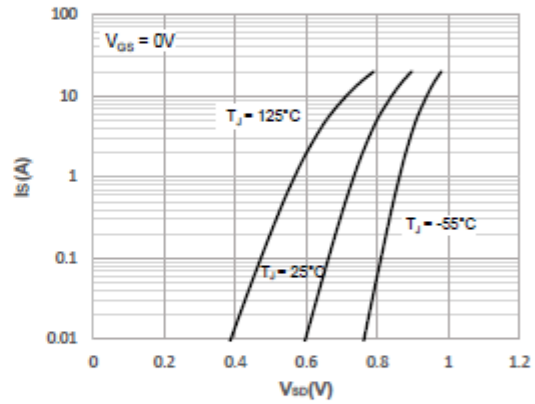


Figure 5: Gate Charge Characteristics

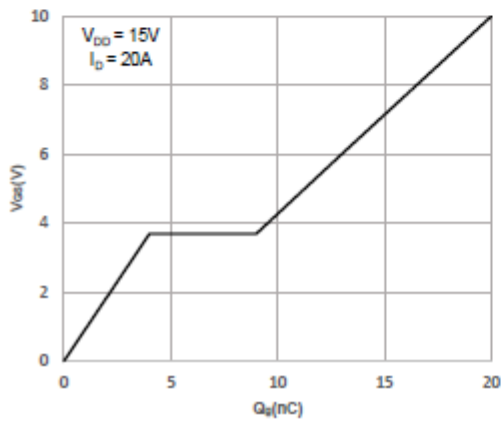


Figure 6: Capacitance Characteristics

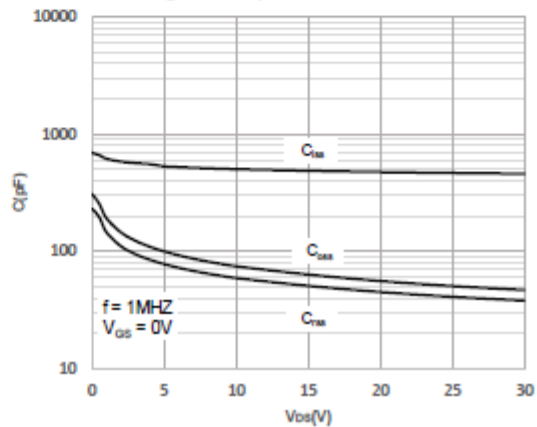


Figure 7: Normalized Breakdown voltage vs. Junction Temperature

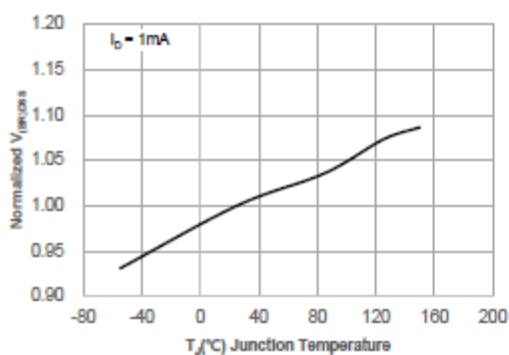


Figure 8: Normalized on Resistance vs. Junction Temperature

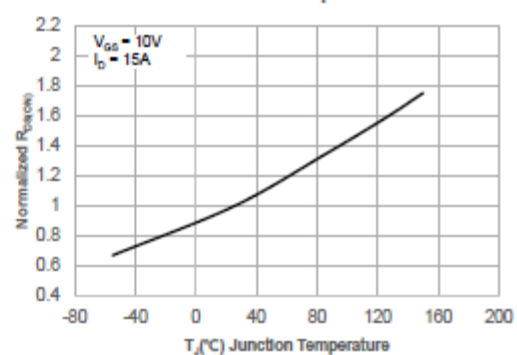




Figure 9: Maximum Safe Operating Area

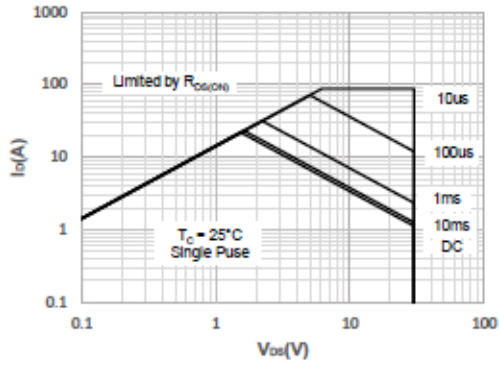


Figure 10: Maximum Continuous Driand Current vs. Case Temperature

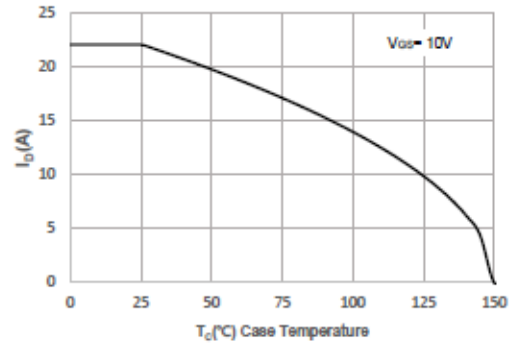


Figure 11: Normalized Maximum Transient Thermal Impedance

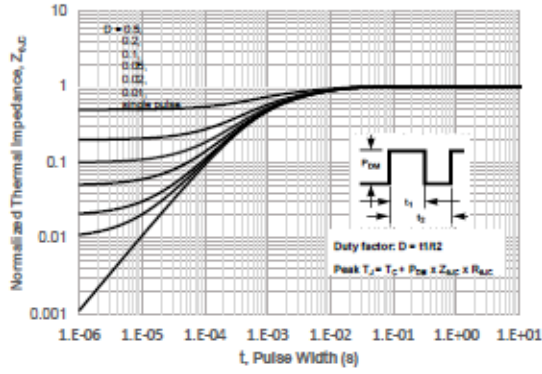
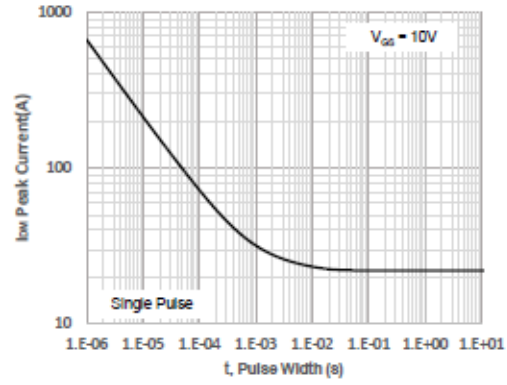


Figure 12: Peak Current Capacity





## Test Circuit

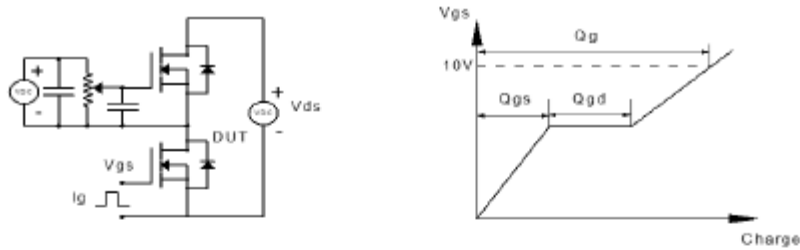


Figure 1: Gate Charge Test Circuit & Waveform

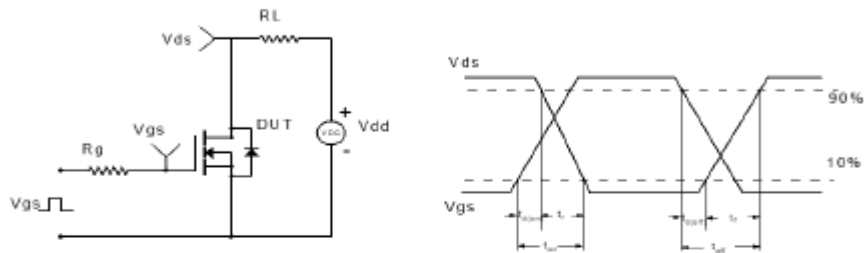


Figure 2: Resistive Switching Test Circuit & Waveform

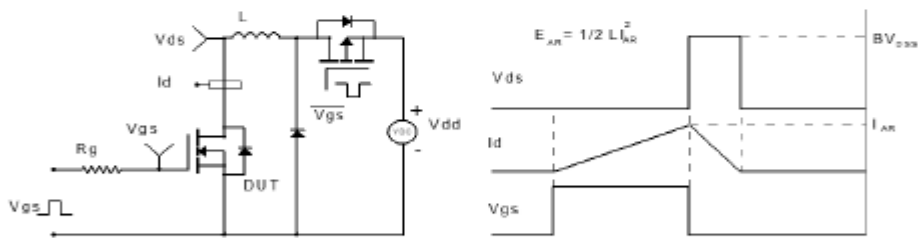


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

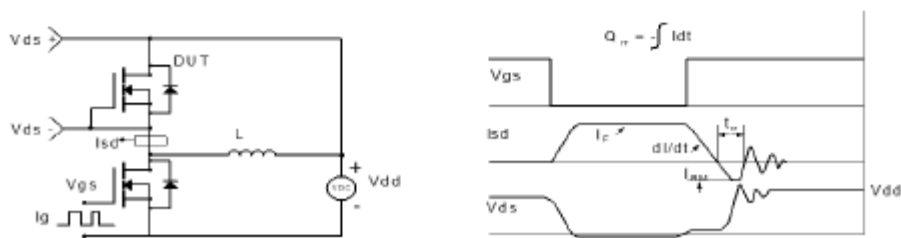
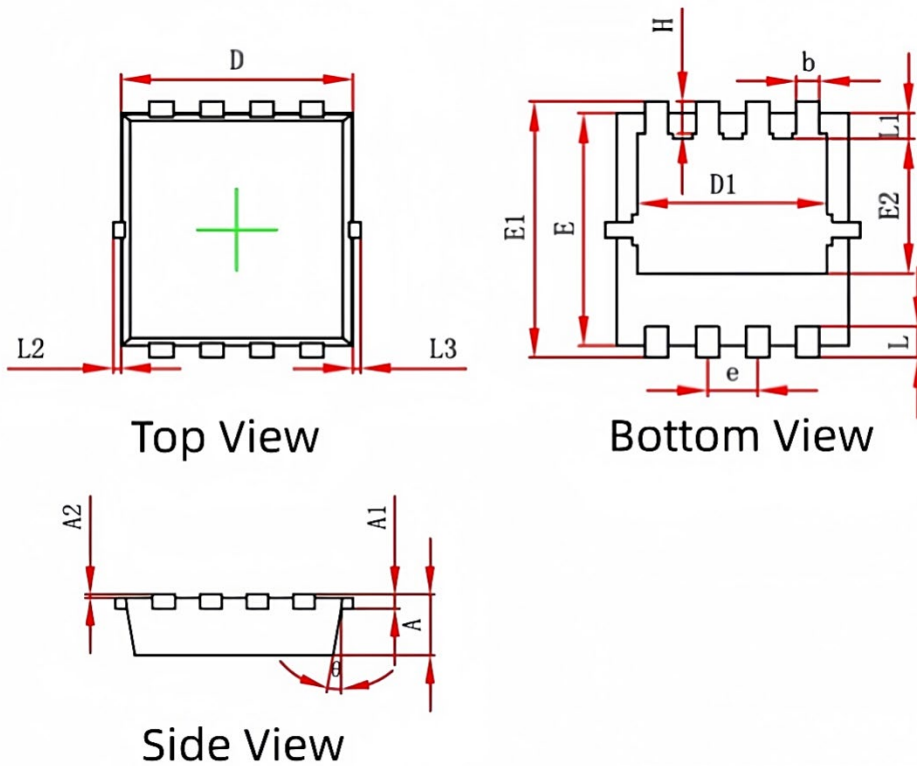


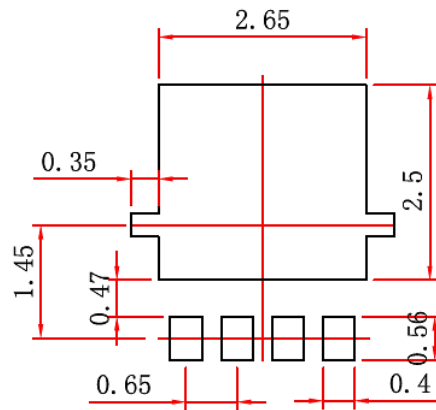
Figure 4: Diode Recovery Test Circuit & Waveform



**Package Mechanical Data(PDFN 3.3x3.3-8)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
$\theta$	9°	13°	9°	13°



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

## Ordering information

Order Code	Package	V <sub>DS</sub> (V)	I <sub>D</sub> (A)	R <sub>DS(ON)</sub> ( mΩ)	
				V <sub>GS</sub> =10V	V <sub>GS</sub> =4.5V
QNM30ND20AJ	PDFN 3.3x3.3-8	30	22	V <sub>GS</sub> =10V	10.4
				V <sub>GS</sub> =4.5V	15.8